RELIABILITY REPORT

FOR

MAX2654EXT

PLASTIC ENCAPSULATED DEVICES

July 10, 2001

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

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Conclusion

The MAX2654 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX2654 high third-order intercept point (IP3), low-noise amplifier (LNA) is designed for applications in GPS, PCS, WLL, and satellite phone systems. The MAX2654 incorporate on-chip internal output matching to 50, eliminating the need for external matching components. A shutdown feature in the MAX2654 reduces the operating current to 0.1µA, eliminating the need for an external supply switch.

The MAX2654 operates in the GPS frequency of 1575MHz with 15.1dB of gain, 1.5dB noise figure, and only consumes 5.8mA.

The MAX2654 operates from a +2.7V to +5.5V single supply and is available in the miniature 6-pin SC70 package.

B. Absolute Maximum Ratings

Item	Rating
V_{CC} to GND	-0.3V to +6V
RF Input Power	+5dBm
Storage Temp.	-65°C to +150°C
Lead Temp. (10 sec.)	+300°C
Power Dissipation	
6-Lead SC70	245mW
Derates above +70°C	
6-Lead SC70	3.1mW/°C

II. Manufacturing Information

A. Description/Function: 1575Mhz Variable-IP3 Low Noise Amplifier

B. Process: GST33

C. Number of Device Transistors: 135

D. Fabrication Location: Oregon, USA

E. Assembly Location: Philippines

F. Date of Initial Production: January, 2001

III. Packaging Information

A. Package Type:	6-Pin SC70
B. Lead Frame:	Alloy 42
C. Lead Finish:	Solder Plate
D. Die Attach:	Non-Conductive
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-7001-0452
H. Flammability Rating:	Class UL94-V0

I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112: Level 1

IV. Die Information

A. Dimensions: 32 x 21 mils

B. Passivation: Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)

C. Interconnect: Poly / Au

D. Backside Metallization: None

E. Minimum Metal Width: Metal1: 1.2; Metal2: 1.2; Metal3: 2.8; Metal4: 5.6 microns (as drawn)

F. Minimum Metal Spacing: Metal1: 1.3; Metal2: 1.4; Metal3: 2.6; Metal4: 2.6 microns (as drawn)

G. Bondpad Dimensions: 5 mil. Sq.

H. Isolation Dielectric: SiO_2

I. Die Separation Method: Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord	(Reliability Lab Manager)
Bryan Preeshl	(Executive Director of QA)
Kenneth Huening	(Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 45 \times 2}$$

1.83 (Chi square value for MTTF upper limit)

4389 Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 2.41 \times 10^{-8}$ λ = 24.1 F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1L**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The WR71-1Z die type has been found to have all pins able to withstand a transient pulse of ± 1500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA and/or ±20V.

Table 1

Reliability Evaluation Test Results

MAX2654EXT

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality (generic test vehicle)	80	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots.

Note 2: Generic process/package data.

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground (e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.